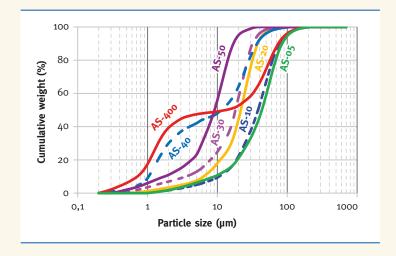
## **AS SERIES**

# Typical properties of common grades

			AS-10	AS-20	AS-30	AS-40	AS-50	AS-400
Chemical Composition	L.O.I <sup>*</sup> *1	%	0.05	0.07	0.09	0.13	0.18	0.09
	Fe <sub>2</sub> O <sub>3</sub>	%	0.04	0.06	0.07	0.06	0.05	0.02
	SiO <sub>2</sub>	%	0.05	0.06	0.06	0.06	0.06	0.03
	Na₂O	%	0.03	0.03	0.03	0.04	0.03	0.03
	Na <sup>+</sup> **	ppm	3	3	3	50	7	32
	Cl <sup>-</sup> *2	ppm	1	1	1	2	1	1
	$Al_2O_3$	%	99.83	99.78	99.75	99.71	99.68	99.87
Mean Particle Size $(d_{50})^{3/3}$		μm	39	22	18	12	9	13
Top cut size		μm	105	75	75 (or 45)	-	75 (or 45)	-
BET Specific Surface area		m²/g	0.5	0.8	1.0	1.2	1.9	1.2
Bulk Density	Loose	g/cm <sup>3</sup>	1.8	1.8	1.6	1.5	1.5	1.4
	Тар	g/cm <sup>3</sup>	2.4	2.4	2.2	2.1	2.0	2.0
Electric Conductivity <sup>*</sup>		μS/cm	3	4	5	31	11	29
Viscosity (Pas)	Epoxy resin (250PHR)		95	110	135	102	130	-
	Silicone resin (600PHR)		124	114	128	106	150	83

\*\*1 Loss On Ignition, \*\*2 Warm water extraction (100°C, 2Hr), \*\*3 LASER DIFFRACTION AND SCATTERING METHOD ANALYZER \*\*4 20g/100ml purified water, \*\*The data shown above are representative figures. They are not guaranteed values.

#### **Particle Size Distribution**



## **Features and Advantages**

- Large particle sizes and broad particle size distributions allow for a high filling density in various resins.
- Roundish shape makes AS Series suitable as a thermal filler with lower viscosity.
- Roundish shape also means a large contact area between particles, increasing thermal conductivity of the compound.
- Bimodal AS-400 is a grade specifically designed for achieving higher filling rates in resins.

### **SEM** images

